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SEMICONDUCTOR DIE PACKAGE
INCLUDING CUP-SHAPED LEADFRAME

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5

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ABSTRACT

1-0

A semiconductor package includes a leadframe which is cup-shaped and holds a semiconductor die. The leadframe is in electrical contact with a terminal on one side of the die, and the leads of the leadframe are bent in such a way that portions of the leads are coplanar with the other side of the die, which also contains one or more terminals. A plastic capsule is formed around the leadframe and die.

15